ABSTRACT

The present invention is directed to a high frequency module used for wireless communication module, and comprises a first organic substrate (11) in which conductive pattern or patterns are formed on the principal surface thereof and one element body (7) or more are mounted, and a second organic substrate (12) in which a recessed portion (22) is formed in correspondence with the area where the element body or bodies (7) are mounted at the connecting surface to the first organic substrate (11). In the state where the second organic substrate (12) is connected to the first organic substrate (11), an element body accommodating portion (24) which seals the element body or bodies (7) is constituted by the recessed portion (22), wherein the element body accommodating portion (24) is adapted so that moisture resistance characteristic and oxidation resistance characteristic are maintained.